**PbFree Product** 



## 1200V, 81A, N-channel SiC power MOSFET

#### **General Description:**

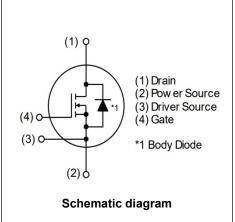
NCES120R018T4 is a SiC MOSFET that contributes to miniaturization and low power consumption of applications. This product achieves industry-leading low on-resistance without sacrificing short-circuit withstand time. This is a 4-pin package type with a driver source terminal that can maximize the high-speed switching performance that is a feature of SiC MOSFETs.

#### **Features**

- Low on-resistance
- Fast switching speed
- Fast reverse recovery
- Easy to parallel
- Simple to drive
- Pb-free lead plating ; RoHS compliant

#### **Application**

- Solar inverters
- DC/DC converters
- Switch mode power supplies
- Induction heating
- Motor drives





TO-247-4L

#### **Package Marking and Ordering Information**

Device	Device Package	Device Marking
NCES120R018T4	TO-247-4L	NCES120R018T4

### Absolute Maximum Ratings (T<sub>C</sub>=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	1200	V
Gate-Source Voltage	V <sub>G</sub> s	-4 to +20	V
Drain Current-Continuous (Note 1)	I <sub>D</sub>	81	А
Drain Current-Continuous(T <sub>C</sub> =100 °C)	I <sub>D</sub> (100℃)	57	Α
Pulsed Drain Current (Note 1)	I <sub>DM</sub>	179	Α
Maximum Power Dissipation	P <sub>D</sub>	312	W
Recommended turn-on gate - source drive voltage	V <sub>G</sub> S_on	+15 to +18	V
Recommended turn-off gate - source drive voltage	V <sub>GS_off</sub>	-4 to 0	V
Virtual junction temperature	T <sub>vj</sub>	175	$^{\circ}$
Operating Junction and Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	-40 To 175	°C



# NCES120R018T4

#### **Thermal Characteristic**

Symbol	Davamatav		l lmita		
Symbol	Parameter	Min	Тур	Max	Units
R <sub>θJC</sub>	Thermal Resistance, Junction to case		0.37	0.48	°C/W

## Electrical Characteristics (T<sub>C</sub>=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics				•		
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =100µA	1200	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =1200V,V <sub>GS</sub> =0V	-	1	-	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =-4V / +20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)	·					
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =10V,I <sub>D</sub> =22.2mA	2.8	-	4.8	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =18V, I <sub>D</sub> =42A	-	18	23.4	mΩ
Gate input resistance	R <sub>G</sub>	f=1MHZ, open drain	-	1	-	Ω
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =10V, I <sub>D</sub> =42A		22		S
Dynamic Characteristics (Note 4)	·					
Input Capacitance	Clss	\/ 000\/\/ 0\/	-	5030	-	pF
Output Capacitance	Coss	V <sub>DS</sub> =800V,V <sub>GS</sub> =0V, f=1MHz	-	141	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>	I – IIVIMZ	-	2	-	pF
Switching Characteristics (Note 4)	·					
Turn-on Delay Time	t <sub>d(on)</sub>		-	13	-	ns
Turn-on Rise Time	t <sub>r</sub>	V <sub>DD</sub> =800V,I <sub>D</sub> =42A V <sub>GS</sub> =+18V	-	21	-	ns
Turn-Off Delay Time	$t_{d(off)}$	/ 0V,R <sub>G</sub> =3.3Ω,L=250μH	-	50	-	ns
Turn-Off Fall Time	t <sub>f</sub>		-	11	-	ns
Total Gate Charge	Qg	\/ -000\/1 -404	-	174	-	nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> =800V,I <sub>D</sub> =42A,	-	42	-	nC
Gate-Drain Charge	$Q_{gd}$	V <sub>GS</sub> =18V	-	48	-	nC
<b>Drain-Source Diode Characteristics</b>				•	,	
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>D</sub> =42A	-	3.4	-	V
Reverse Recovery Time	t <sub>rr</sub>	T 05°0 I 404 V 000V	-	12		ns
Reverse Recovery Charge	Qrr	$T_J = 25^{\circ}C$ , $I_F = 42A$ , $V_R = 800V$ ,	-	252		ns
Peak reverse recovery current	I <sub>rrm</sub>	di/dt = 4700A/µs <sup>(Note3)</sup>		44		Α

#### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. PW  $\leq$  10 $\mu$ s, Duty cycle  $\leq$  1%
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production

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#### **Test Circuit**

Fig.1-1 Gate Charge Measurement Circuit

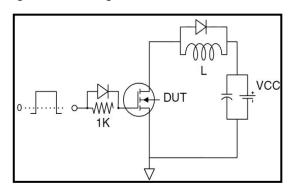


Fig.1-2 Gate Charge Waveform

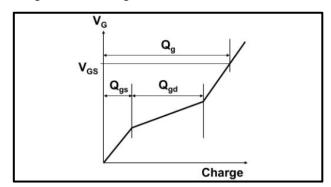


Fig.2-1 Switching Characteristics Measurement Circuit

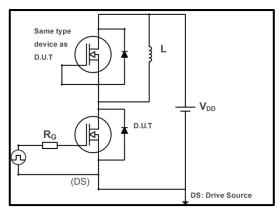
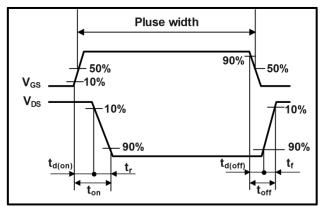


Fig.2-2 Waveforms for Switching Time



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#### **Typical Electrical and Thermal Characteristics**

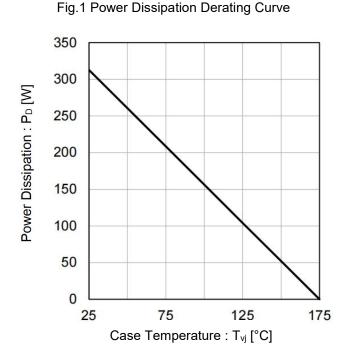


Fig.2 Maximum Safe Operating Area

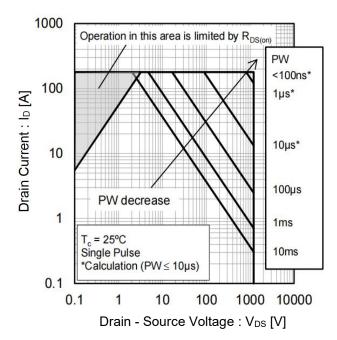


Fig.3 Typical Transient Thermal Impedance vs. Pulse Width

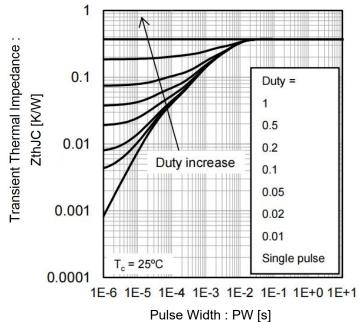
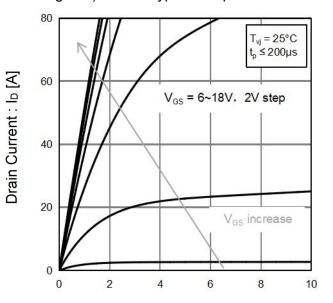


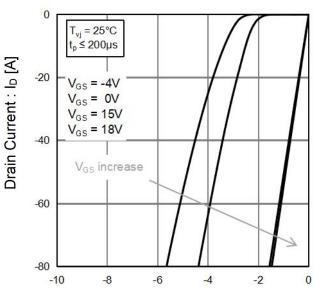


Fig.4  $T_{vj}$  = 25°C Typical Output Characteristics



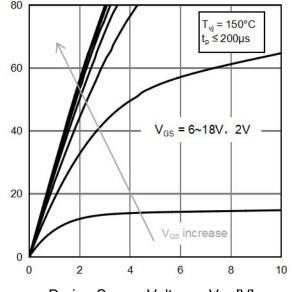
Drain - Source Voltage: V<sub>DS</sub> [V]

Fig.5 T<sub>vj</sub> = 25°C 3rd Quadrant Characteristics



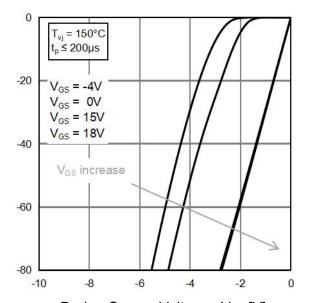
Drain - Source Voltage: V<sub>DS</sub> [V]

Fig.6 T<sub>vj</sub> = 150°C Typical Output Characteristics



Drain - Source Voltage: VDS [V]

Fig.7  $T_{vj}$  = 150°C 3rd Quadrant Characteristics



Drain - Source Voltage: VDS [V]

Drain Current : I<sub>D</sub> [A]

Drain Current : I<sub>D</sub> [A]



Fig.8 Typical Transfer Characteristics

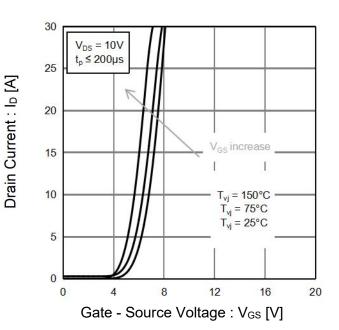


Fig.9 Static Drain - Source On - State
Resistance vs. Gate - Source Voltage

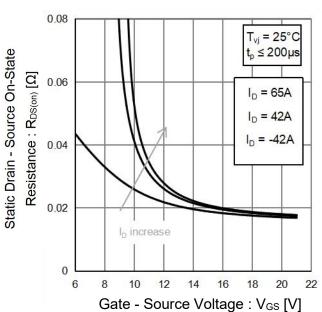


Fig.10 Static Drain - Source On - State Resistance vs. Drain Current

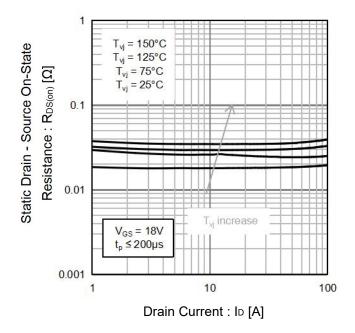


Fig.11 Body Diode Forward Voltage vs. Gate - Source Voltage

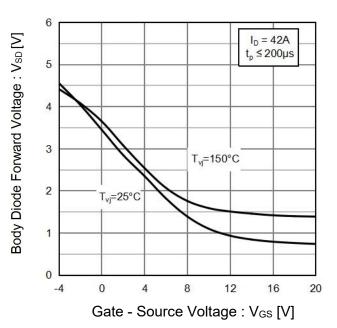
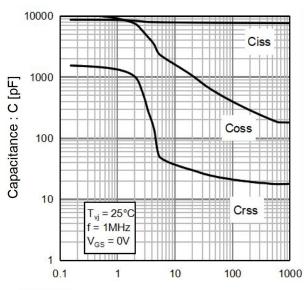


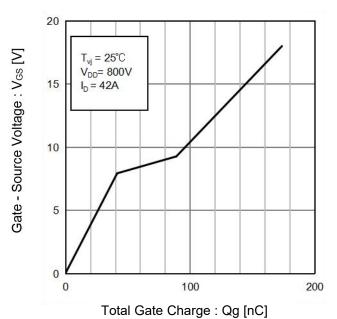


Fig.12 Typical Capacitance vs. Drain - Source Voltage



Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.13 Dynamic Input Characteristics

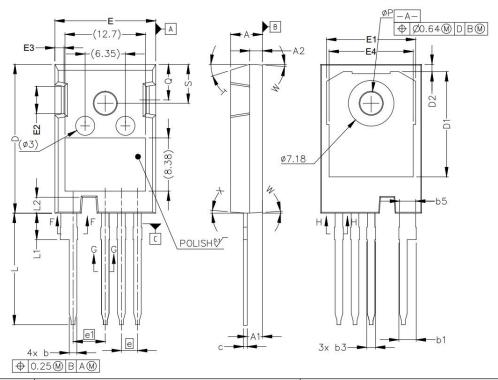


V1.0

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# **TO-247-4L Package Information**



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	4.83	5.21	0.19	0.21	
A1	2.29	2.54	0.09	0.10	
A2	1.91	2.16	0.08	0.09	
b1	2.39	2.94	0.09	0.12	
b3	1.07	1.60	0.04	0.06	
b5	2.39	2.69	0.09	0.11	
С	0.55	0.68	0.02	0.03	
D	23.30	23.60	0.92	0.93	
D1	16.25	17.65	0.64	0.69	
D2	0.95	1.25	0.04	0.05	
E	15.75	16.13	0.62	0.64	
E1	13.10	14.15	0.52	0.56	
E2	3.68	5.10	0.14	0.20	
E3	1.00	1.90	0.04	0.07	
E4	12.38	13.43	0.49	0.53	
е	2.54	2.54 BSC		SC	
e1	5.08	BSC	0.2 B	SC	
L	17.31	17.82	0.68	0.70	
L1	3.97	4.37	0.16	0.17	
L2	2.35	2.65	0.09	0.10	
ФР	3.51	3.65	0.14	0.14	
Q	5.49	6.00	0.22	0.24	
S	6.04	6.30	0.24	0.25	
Т	17.5°	REF.	0.69° F	REF.	
W	3.5° l	REF.	0.14° F	REF.	
X	4.0° l	REF.	0.16° REF.		



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